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Description

The 74LVC2G14 is a dual Schmitt trigger inverter gate with standard push-pull outputs. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using I_{OFF}. The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down.

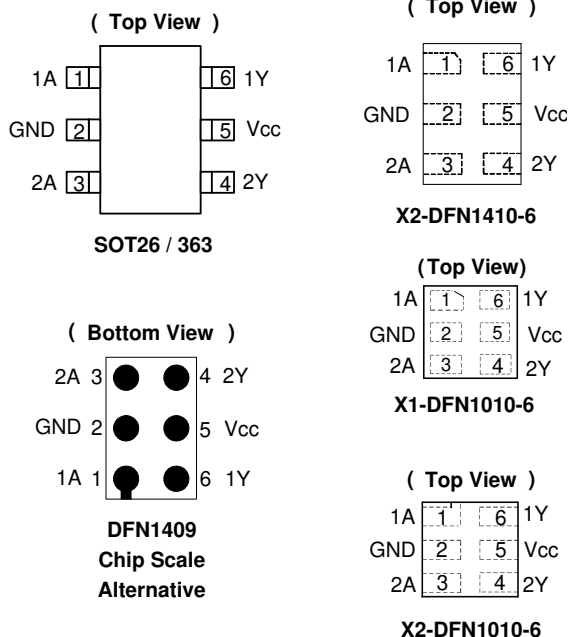
The gate performs the positive Boolean function:

$$Y = \overline{A}$$

Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- ±24mA Output Drive at 3.0V
- CMOS Low Power Consumption
- IOFF Supports Partial-Power-Down Mode Operation
- Inputs Accept up to 5.5V
- ESD Protection Tested per JESD 22
 - Exceeds 200-V Machine Model (A115)
 - Exceeds 2000-V Human Body Model (A114)
 - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- DFN1409 Package Designed as a Direct Replacement for Chip Scale Packaging
- Range of Package Options SOT26, SOT363, X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6, and X2-DFN1410-6
- Leadless Packages Named per JESD30E
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Pin Assignments



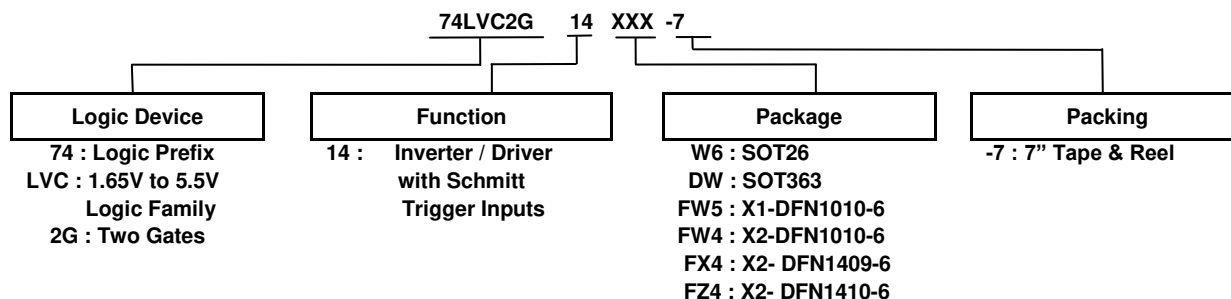
Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products Such As:
 - PCs, Networking, Notebooks, Netbooks, Tablets
 - Computer Peripherals, Hard Drives, SSD, CD/DVD ROM
 - TV, DVD, DVR, Set Top Box
 - Cell Phones, Personal Navigation / GPS
 - MP3 Players, Cameras, Video Recorders

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Ordering Information



Part Number	Package Code	Package (Note 4)	Package Size	7" Tape and Reel (Note 5)	
				Quantity	Part Number Suffix
74LVC2G14W6-7	W6	SOT26	2.8mm X 2.2 mm X 1.1mm 0.95 mm lead pitch	3000/Tape & Reel	-7
74LVC2G14DW-7	DW	SOT363	2.0mm X 2.0mm X 1.1mm 0.65 mm lead pitch	3000/Tape & Reel	-7
74LVC2G14FW5-7	FW5	X1-DFN1010-6	1.0mm X 1.0mm X 0.5mm 0.35 mm pad pitch	5000/Tape & Reel	-7
74LVC2G14FW4-7	FW4	X2-DFN1010-6	1.0mm X 1.0mm X 0.4mm 0.35 mm pad pitch	5000/Tape & Reel	-7
74LVC2G14FX4-7	FX4	X2-DFN1409-6 Chip Scale Alternative	1.4mm X 0.9mm X 0.4mm 0.5 mm pad pitch	5000/Tape & Reel	-7
74LVC2G14FZ4-7	FZ4	X2-DFN1410-6	1.4mm X 1.0mm X 0.4mm 0.5 mm pad pitch	5000/Tape & Reel	-7

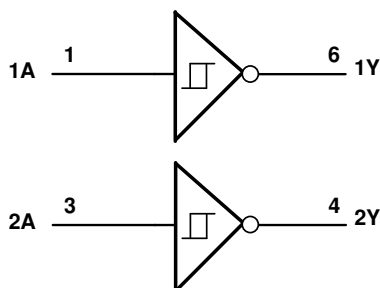
Notes: 4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

5. The taping orientation is located on our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Pin Descriptions

Pin Name	Pin Number	Function
1A	1	Data Input
GND	2	Ground
2A	3	Data Input
2Y	4	Data Output
V _{CC}	5	Supply Voltage
1Y	6	Data Output

Logic Diagram



Function Table

Inputs	Output
A	Y
H	L
L	H

Absolute Maximum Ratings (Notes 6 and 7) (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to +6.5	V
V_I	Input Voltage Range	-0.5 to +6.5	V
V_O	Voltage Applied to Output in High Impedance or I_{OFF} State	-0.5 to +6.5	V
V_O	Voltage Applied to Output in High or Low State	-0.3 to $V_{CC} + 0.5$	V
I_{IK}	Input Clamp Current $V_I < 0$	-50	mA
I_{OK}	Output Clamp Current $V_O < 0$	-50	mA
I_O	Continuous Output Current	-50	mA
—	Continuous Current Through V_{DD} or GND	± 100	mA
T_J	Operating Junction Temperature	-40 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature	-65 to +150	$^\circ\text{C}$

- Note: 6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
 7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 8) (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Min	Max	Unit	
V_{CC}	Operating Voltage	Operating	1.65	5.5	V
		Data retention only	1.5	—	V
V_I	Input Voltage	0	5.5	V	
V_O	Output Voltage	0	V_{CC}	V	
I_{OH}	High-Level Output Current	$V_{CC} = 1.65\text{V}$	—	-4	mA
		$V_{CC} = 2.3\text{V}$	—	-8	
		$V_{CC} = 3\text{V}$	—	-16	
		$V_{CC} = 4.5\text{V}$	—	-24	
I_{OL}	Low-Level Output Current	$V_{CC} = 1.65\text{V}$	—	4	mA
		$V_{CC} = 2.3\text{V}$	—	8	
		$V_{CC} = 3\text{V}$	—	16	
		$V_{CC} = 4.5\text{V}$	—	24	
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	$V_{CC} = 1.8\text{V} \pm 0.15\text{V}, 2.5\text{V} \pm 0.2\text{V}$	—	20	ns/V
		$V_{CC} = 3.3\text{V} \pm 0.3\text{V}$	—	10	
		$V_{CC} = 5\text{V} \pm 0.5\text{V}$	—	5	
T_A	Operating Free-air Temperature	—	-40	+125	$^\circ\text{C}$

- Note: 8. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V_{CC}	-40°C to +85°C		-40°C to +125°C		Unit	
				Min	Max	Min	Max		
V_{T+}	Positive-going Input Threshold Voltage	—	1.8V	0.70	1.50	0.70	1.70	V	
			2.3V	1.00	1.80	1.00	2.00		
			3V	1.30	2.20	1.30	2.40		
			4.5V	1.90	3.10	1.90	3.30		
			5.5V	2.20	3.60	2.20	3.80		
V_{T-}	Negative-going Input Threshold Voltage	—	1.65V	0.25	0.90	0.39	1.10	V	
			2.3V	0.40	1.15	0.25	0.87		
			3V	0.60	1.50	0.40	1.35		
			4.5V	1.00	2.00	0.60	1.70		
			5.5V	1.20	2.30	1.00	2.50		
ΔV_T	Hysteresis ($V_{T+} - V_{T-}$)	—	1.8V	0.15	1.00	0.37	1.20	V	
			2.3V	0.25	1.10	0.15	1.30		
			3V	0.40	1.20	0.40	1.40		
			4.5V	0.60	1.50	0.60	1.70		
			5.5V	0.70	1.70	0.70	1.90		
V_{OH}	High-Level Output Voltage	$I_{OH} = -100\mu\text{A}$	1.65V to 4.5V	$V_{CC} - 0.1$	—	$V_{CC} - 0.1$	—	V	
		$I_{OH} = -4\text{mA}$	1.65V	1.2	—	0.95	—		
		$I_{OH} = -8\text{mA}$	2.3V	1.9	—	1.7	—		
		$I_{OH} = -16\text{mA}$	3V	2.4	—	1.9	—		
		$I_{OH} = -24\text{mA}$		2.3	—	2.0	—		
		$I_{OH} = -32\text{mA}$	4.5V	3.8	—	3.4	—		
V_{OL}	Low-Level Output Voltage	$I_{OL} = 100\mu\text{A}$	1.65V to 4.5V	—	0.1	—	0.10	V	
		$I_{OL} = 4\text{mA}$	1.65V	—	0.45	—	0.70		
		$I_{OL} = 8\text{mA}$	2.3V	—	0.3	—	0.45		
		$I_{OL} = 16\text{mA}$	3V	—	—	0.4	—		0.60
		$I_{OL} = 24\text{mA}$		—	—	0.55	—		0.80
		$I_{OL} = 32\text{mA}$	4.5V	—	—	0.55	—		0.80
I_I	Input Current	$V_I = 5.5\text{V}$ or GND	0 to 5.5V	—	± 5	—	± 20	μA	
I_{OFF}	Power Down Leakage Current	V_I or $V_O = 5.5\text{V}$	0	—	± 10	—	± 20	μA	
I_{CC}	Supply Current	$V_I = 5.5\text{V}$ or GND, $I_O = 0$	1.65V to 5.5V	—	10	—	40	μA	

Package Characteristics (@ $T_A = +25^\circ\text{C}$, $V_{CC} = 3.3\text{V}$, unless otherwise specified.)

Symbol	Parameter	Package	Conditions	Min	Typ	Max	Unit
C_I	Input Capacitance	Typical of all packages	$V_{CC} = 3.3\text{V}$ $V_I = V_{CC}$ or GND	—	3.5	—	pF
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT26	(Note 9)	—	204	—	$^\circ\text{C/W}$
		SOT363		—	371	—	
		X2-DFN1410-6		—	430	—	
		X2-DFN1409-6		—	450	—	
		X1-DFN1010-6		—	495	—	
		X2-DFN1010-6		—	510	—	
θ_{JC}	Thermal Resistance Junction-to-Case	SOT26	(Note 9)	—	52	—	$^\circ\text{C/W}$
		SOT363		—	143	—	
		X2-DFN1410-6		—	190	—	
		X2-DFN1409-6		—	225	—	
		X1-DFN1010-6		—	245	—	
		X2-DFN1010-6		—	250	—	

Note: 9. Test condition for all packages: : Device mounted on FR-4 substrate PC board, 2oz copper with minimum recommended pad layout.

Switching Characteristics

$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $C_L = 30$ or 50pF (see Figure 1)

Parameter	From (Input)	TO (OUTPUT)	$V_{CC} = 1.8\text{V} \pm 0.15\text{V}$		$V_{CC} = 2.5\text{V} \pm 0.2\text{V}$		$V_{CC} = 3.3\text{V} \pm 0.3\text{V}$		$V_{CC} = 5\text{V} \pm 0.5\text{V}$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	A	Y	0.5	11.0	0.5	6.5	0.5	6.0	0.5	4.3	ns

$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$, $C_L = 30$ or 50pF (see Figure 1)

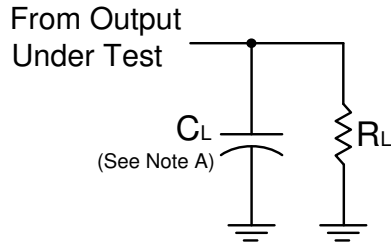
Parameter	From (Input)	TO (OUTPUT)	$V_{CC} = 1.8\text{V} \pm 0.15\text{V}$		$V_{CC} = 2.5\text{V} \pm 0.2\text{V}$		$V_{CC} = 3.3\text{V} \pm 0.3\text{V}$		$V_{CC} = 5\text{V} \pm 0.5\text{V}$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	A	Y	0.5	12.0	0.5	7.2	0.5	6.7	0.5	4.7	ns

Operating Characteristics

$T_A = +25^\circ\text{C}$

Parameter	Test Conditions	$V_{CC} = 1.8\text{V}$	$V_{CC} = 2.5\text{V}$	$V_{CC} = 3.3\text{V}$	$V_{CC} = 5\text{V}$	Unit
		Typ	Typ	Typ	Typ	
C_{PD}	Power Dissipation Capacitance $f = 10\text{MHz}$	17	19	20	21	pF

Parameter Measurement Information



V _{CC}	Inputs		V _M	C _L	R _L
	V _I	t _R /t _F			
1.8V±0.15V	V _{CC}	≤2ns	V _{CC} /2	30 pF	1kΩ
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	30 pF	500Ω
3.3V±0.3V	3V	≤2.5ns	1.5V	50 pF	500Ω
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	50 pF	500Ω

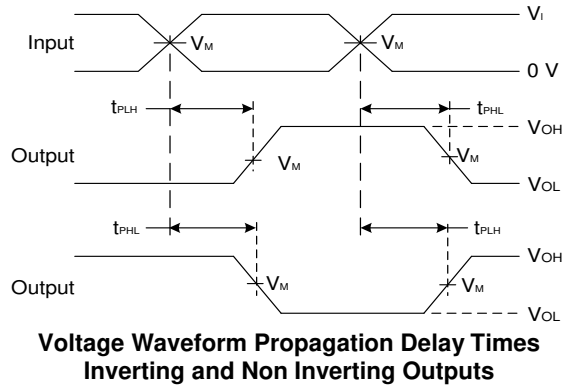
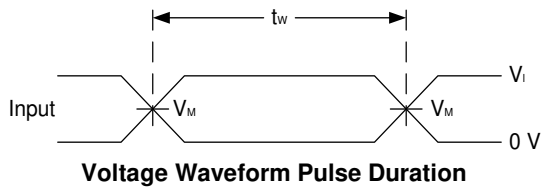
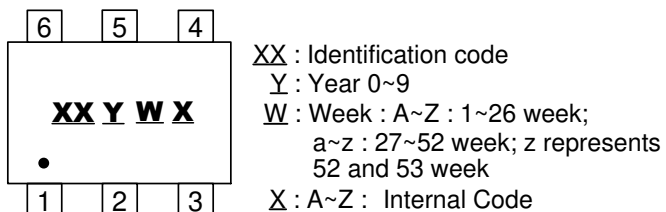


Figure 1. Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10MHz.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD}.

Marking Information

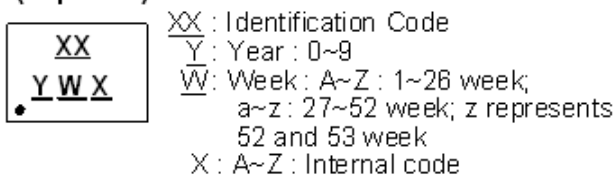
(1) SOT26, SOT363



Part Number	Package	Identification Code
74LVC2G14W6-7	SOT26	Z5
74LVC2G14DW-7	SOT363	Z5

(2) X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6, X2-DFN1410-6

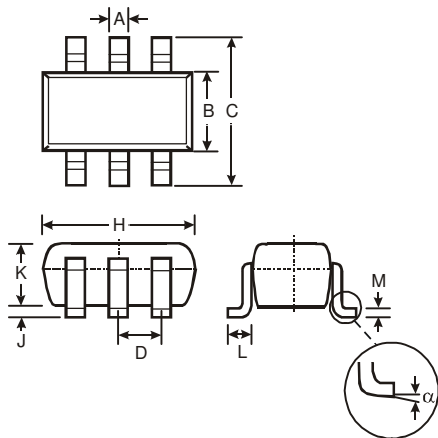
(Top View)



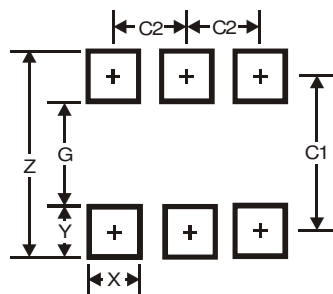
Part Number	Package	Identification Code
74LVC2G14FW4-7	X2-DFN1010-6	Z5
74LVC2G14FW5-7	X1-DFN1010-6	W5
74LVC2G14FX4-7	X2-DFN1409-6	X5
74LVC2G14FZ4-7	X2-DFN1410-6	Z5

SOT26 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



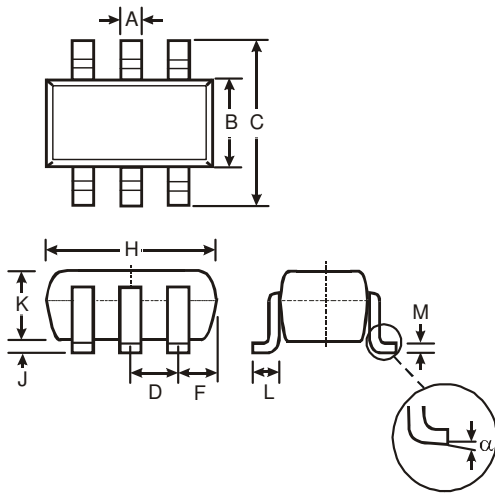
SOT26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			



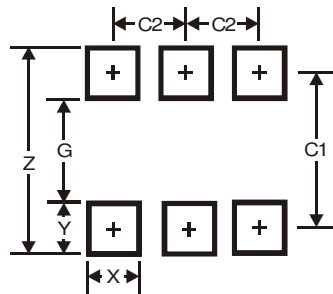
Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

SOT363 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



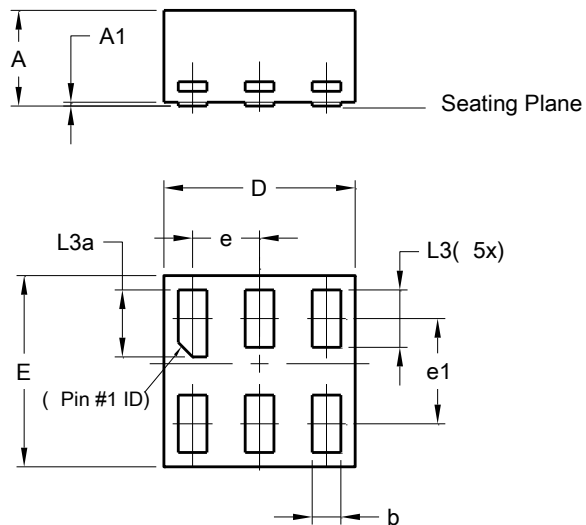
SOT363			
Dim	Min	Max	Typ
A	0.10	0.30	0.25
B	1.15	1.35	1.30
C	2.00	2.20	2.10
D	0.65 Typ		
F	0.40	0.45	0.425
H	1.80	2.20	2.15
J	0	0.10	0.05
K	0.90	1.00	1.00
L	0.25	0.40	0.30
M	0.10	0.22	0.11
α	0°	8°	-
All Dimensions in mm			



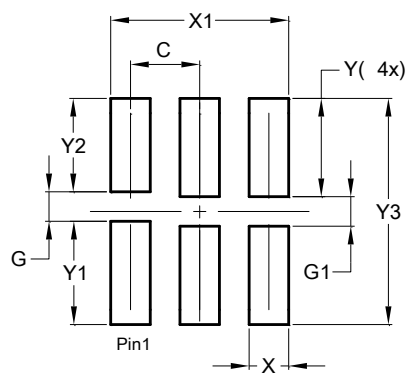
Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

X1-DFN1010-6 (Type B) Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



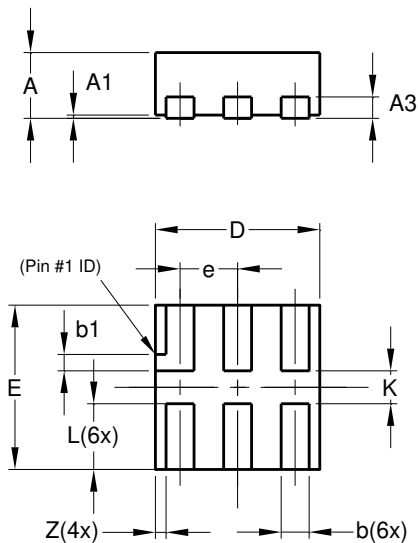
X1-DFN1010-6 (Type B)			
Dim	Min	Max	Typ
A	-	0.50	0.39
A1	-	0.04	-
b	0.12	0.20	0.15
D	0.95	1.050	1.00
E	0.95	1.050	1.00
e	0.35 BSC		
e1	0.55 BSC		
L3	0.27	0.30	0.30
L3a	0.32	0.40	0.35
All Dimensions in mm			



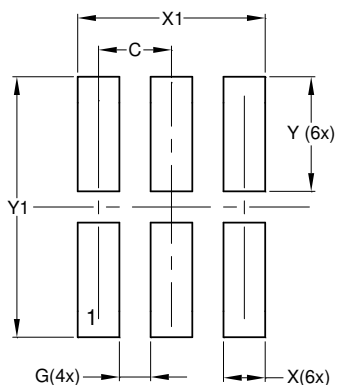
Dimensions	Value (in mm)
C	0.350
G	0.150
G1	0.150
X	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

X2-DFN1010-6 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



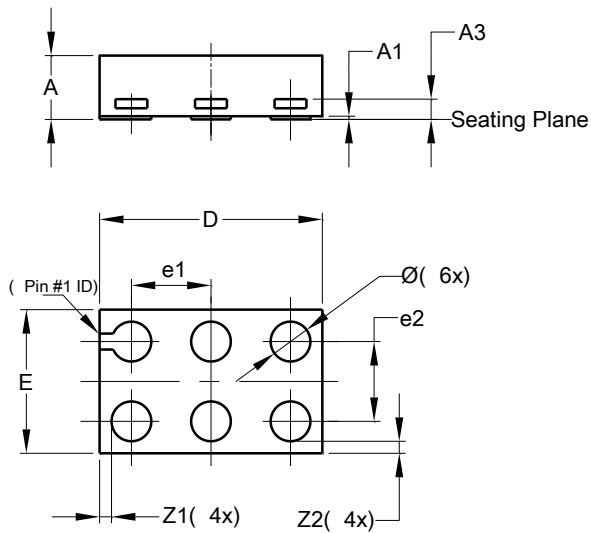
X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			



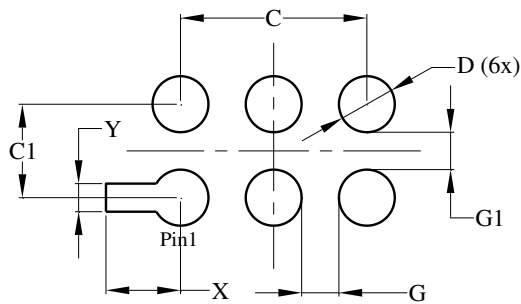
Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

X2-DFN1409-6 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



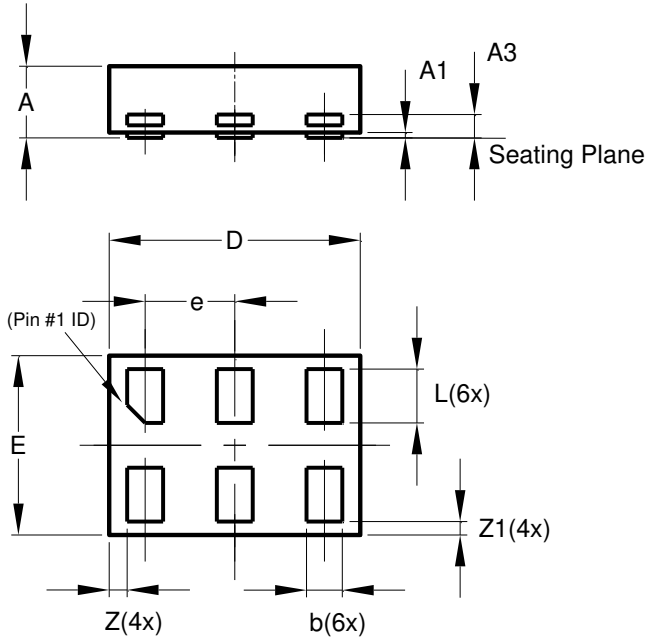
X2-DFN1409-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0	0.05	0.02
A3	—	—	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	—	—	0.50
e2	—	—	0.50
Z1	—	—	0.075
Z2	—	—	0.075
All Dimensions in mm			



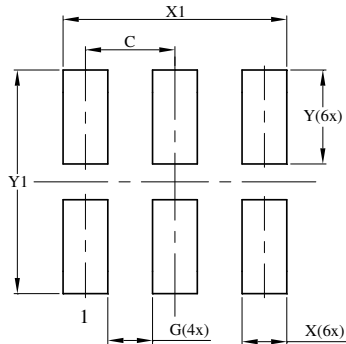
Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

X2-DFN1410-6 Package Outline Dimensions and Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

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